Product Change Notification

112907 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Intel Mobile Communications Contacts

Americas Email: IMC.PCN.ASMO@intel.com
Asia Pacific Email: IMC.PCN.APAC@intel.com
Europe Email: IMC.PCN.EMEA@intel.com
Japan Email: IMC.PCN.IJKK@intel.com
Korea Email: IMC.PCN.KOREA@intel.com
PROC APAC Email: IMC.PCN.PROC@intel.com

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Product Change Notification

Change Notification #:	**112907 - 00**
Change Title:	**Intel® X-GOLD™ 716G PCN 112907-00, Manufacturing Site, Additional Wafer Production Sites**
Date of Publication:	**February 28, 2014**

Key Characteristics of the Change:

Manufacturing Site

Forecasted Key Milestones:

Date of Samples Availability:	March 28, 2014
Date of Qualification Data Availability:	May 23, 2014
Date Customer Must be Ready to Receive Post-Conversion Material:	June 27, 2014

Description of Change to the Customer:

In order to secure capacity, and to increase flexibility regarding customer demand for the Intel® X-GOLD™ 716G PMB9923.P10 production, Intel is introducing additional wafer production sites; Global Foundries Singapore for digital baseband chip and Winbond for LPDDR2 memory chip.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any change to the package size, function or reliability (reliability documented see Device Description). Global Foundries and Winbond are qualified Manufacturing Sites for Intel.

No actions are needed from customers.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#
Intel® X-GOLD™ 716G	PMB9923.P10	S LK7A	929178
Intel® X-GOLD™ 716G	PMB9923.P10	S LK8C	929586
Intel® X-GOLD™ 716G	PMB9923.P10	S LKDU	933237

Please contact your local Intel Mobile Communications representative for further technical questions.

PCN Owner

Georg Walter: georg.walter@intel.com

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 28, 2014	00	Originally Published PCN